

WINTER

Diamond Coated Wire

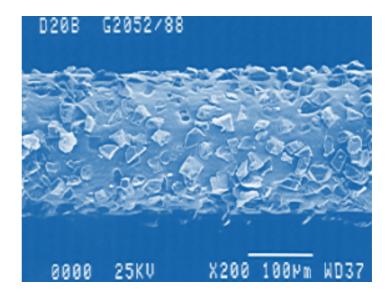
(electroplated)

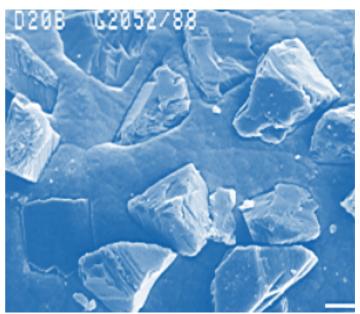
Preferably used for the cutting of hard, brittle materials like:

- Silicon
- Silicon carbide
- Sapphire
- Apart from the environmental advantage, this wire also permits considerably higher cutting speed than the conventional method using wire with slurry.
- Available up to a length of 4,000 metres
- Available
 diameters:
 230 µm
 (grit size D20B)
 for Si
 350 µm
 (grit size D25)
 for SiC or sapphire

SEM pictures of electroplated diamond coated wire

(various magnifications)







Diamond Coated Wire (electroplated)

Diamond coated wire (cross section)

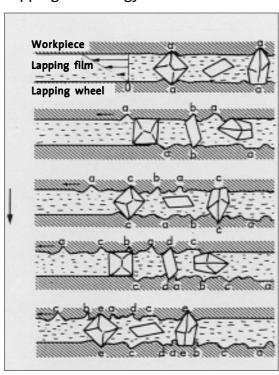


View into machine with diamond coated wire ready for cutting



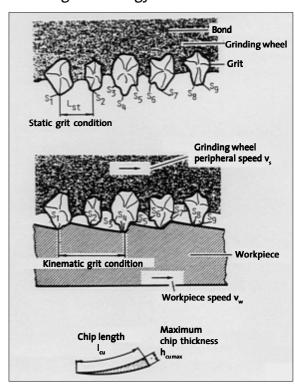
Difference in the technology of lapping and grinding

Lapping technology



- Rolling and fixed grits
- Crack inducing method
- Material removal by crack system in the surface
- Multi directional scratches

Grinding technology



- · Fixed grits
- · Chip removing method
- Material removal by statistical chip thickness
- Producing directed relative speed between grits and workpiece



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Certified acc. to DIN EN ISO 14001 Certifcate No. EM-2129 HH



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